ADVACAM

Ref. no: IEAP\_25112019-l

Date: 25.11.2019

Imaging the Unseen

To: IEAP CTU in Prague, Horská 3a/22, CZ-128 00 Praha 2 - Albertov, Czech Republic

Offer for Si planar 300 um single sensor chips

Dear,

Advacam offers TPIX - Si planar 300 um single sensor modules as follows:

Task #1: TPIX3 - Si planar 300 um single sensor modules:

20 pcs of Si planar 300 um thick single sensor chips with UBM and pixel array of 257 x 256. "SRv3" single Si sensors with size 16.31 mm x 16.31 mm will be used for this work.

Flip chip bonding of lEAP's TPIX3 ASICs stored at Advacam to Si sensors. Flip chip bonding cost will be covered by an existing IEAP purchase order# 3520180359.

IV characteristics of the sensor modules will be measured after flip chip bonding.

Specifications:

o Full depletion voltage: typically < 40 V, Max 60 V.

o Breakdown voltage (10 pA): Min 200 V, Typically > 500V

o Guard leakage current (measured in dark at 20 C): < 100 nA per cm2 at 100 V Price: 11,200 € (560 € per sensor chip)

Task #2: Preparing the material for shipping

Documentation, materials, packing etc.

Dispatch of goods in one batch.

Price: €

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Page 1 of 2

Ref. no: IEAP\_2S112019-l

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| **Task** | **Name** | **No. of units** | **Unit price** | **Price** |
| 1 | TPIX3 -Si planar 300 um single sensor modules | 20 | €00 | €00 |
| 2 | Preparing material for shipping | 1 | €0,00 | €00 |
|  |  |  | Total | € |

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| --- | --- |
| Payments: | The total price of the commission is ll,600€. The invoice will be sent immediately after the PO has been processed. The VAT or any other taxes and fees imposed by the foreign authorities or customs shall be added to the price, when applicable. |
| Validity Period: | This quotation is valid for one month starting from the date of the offer. |

**ADVACAM s.r.o**